

RMA201 IN97-AG3 SOLDER PASTE

FEATURES

- ▶ Large Process Window
- ▶ High Humidity Resistance
- ▶ Low Melting Temperature 143°C
- ▶ Aqueous Clean With Saponifier

DESCRIPTION

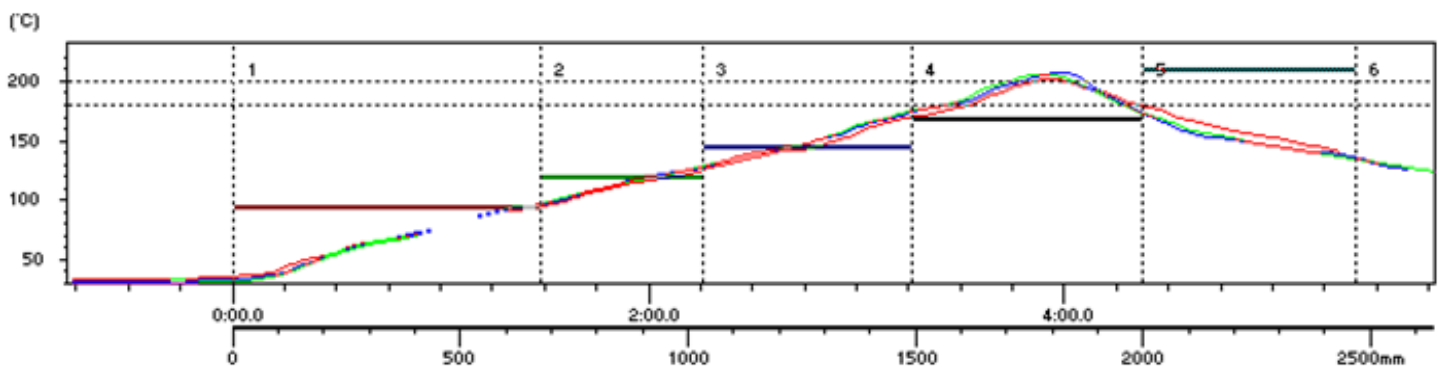
RMA201 is a mildly activated rosin-based solder paste. RMA201 has been developed for use in conjunction with low melting temperature alloys, including indium- and bismuth-bearing alloys. RMA201 has a wide process window, in addition to a good activity level, which allows the product to accommodate a variety of environments and process applications. RMA201 performs well in continuous production, offers good slump resistance, high tack, excellent wetting, and low post-process residues.

STANDARD PASTE COMPOSITION

Application Method	IPC Powder Size	Metal Load
Standard Stencil Printing	3	89%
Fine Pitch Stencil Printing	5	88.5%
Ultra-Fine Pitch Stencil Printing	5	88%
Dispensing Syringes	3	84%

Note: These are typical starting guidelines. To achieve optimal performance, actual metal load and particle size may vary per process, application, and environment.

REFLOW PROFILE



Rate of Rise 2-3° C / Sec Max	Pre-Heat Ramp to 75°C	Progress Through 100°C-120°C	Directly to Reflow 175°C ± 5°C	Time Above 143°C	Cooldown ≤ 4°C
-	≤ 90 Sec	10-30 Sec	-	45 - 60 Sec	-

PRINTER SETUP

Recommended Initial Printer Settings – Dependent on PCB and Pad Design	
Parameter	Recommended Initial Settings
Squeegee Pressure	1 – 1.5 lbs/inch of blade
Squeegee Speed	.5 – 6 inches/second
Snap-off Distance	On Contact 0.00 mm
PCB Separation Distance	0.030 - .050”
PCB Separation Speed	Medium

PASTE APPLICATION

Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle. A bead diameter of 1/2 to 5/8 inch is normally sufficient to begin. Apply small amounts of fresh solder paste to the stencil at frequent, controlled intervals to maintain paste chemistry and workable properties. Cleaning of your stencil will vary according to the application; however, it can be accomplished using AIM DJAW stencil cleaner. Use DJAW in moderation and remove any excess cleaner from stencil.

PLACEMENT INFORMATION

RMA201 provides the necessary tack time/force for today’s high-speed placement equipment. Ensuring proper support of PCBs during assembly and handling will enhance product performance and reliability.

HANDLING & STORAGE

- RMA201 In97-Ag3 has a 1 month shelf life when frozen.
- Allow the solder paste to completely warm naturally to ambient temperature (8 hours is recommended) prior to breaking seal for use.
- Mix the product lightly and thoroughly for 1 to 3 minutes to ensure even distribution of any separated material resulting from storage.
- Do not store new and used paste in the same container. Re-seal any opened containers while not in use.
- Replace the internal plug in conjunction with the cap of the 500 gram jar to ensure the best possible seal.

CLEANING

RMA201 can be cleaned if necessary, with saponified tap water. We recommend AIMTERGE 520; however, deionized water is recommended for the final rinse. A temperature of 212°C-302°C (100°F-150°F) is sufficient for removing any residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.